



Never stop thinking

# IFX24401

Low Dropout Voltage Regulator

IFX24401TEV50

IFX24401ELV50

## Data Sheet

Rev. 1.02, 2009-12-10

Standard Power

**RoHS**

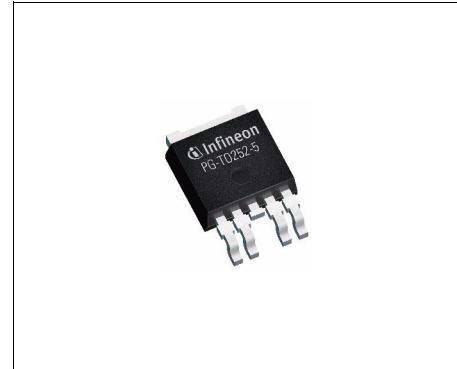

## 1 Overview

### Features

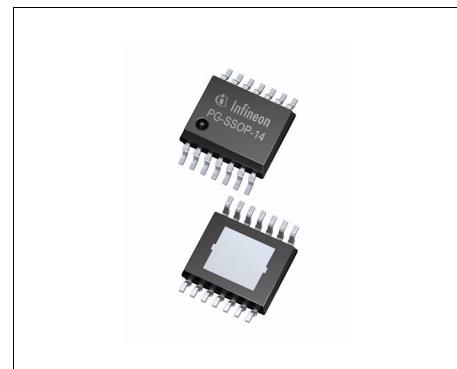
- Output voltage  $5\text{ V} \pm 2\%$
- Ultra low current consumption:  $20\text{ }\mu\text{A}$  (typ.)
- 300 mA current capability
- Enable input
- Very low-drop voltage
- Short circuit protection
- Overtemperature protection
- Low Dropout Voltage, 250mV (typ.)
- High Input Voltage 45 V
- Temperature Range  $-40^\circ\text{C} \leq T_j \leq 125^\circ\text{C}$
- Green Product (RoHS compliant)

### Applications

- Battery powered devices (e.g. Handheld GPS)
- Portable Radios
- HDTV Televisions
- Game Consoles
- Network Routers



**PG-T0252-5**



**PG-SSOP-14**

For automotive and transportation applications, please refer to the Infineon TLE and TLF voltage regulator series.

### Functional Description

The IFX24401 is a monolithic integrated low-drop voltage regulator for load currents up to 300 mA. The output voltage is regulated to  $V_{Q,\text{nom}} = 5.0\text{ V}$  with an accuracy of  $\pm 2\%$ . A sophisticated design allows stable operation with low ESR ceramic output capacitors down to 470 nF. The device is designed for the harsh environments. Therefore it is protected against overload, short circuit and overtemperature conditions. Due to its ultra low stand-by current consumption of  $20\text{ }\mu\text{A}$  (typ.) the IFX24401 is ideal for use in battery powered applications. The regulator can be shut down via an Enable input which further reduces the current consumption to  $5\text{ }\mu\text{A}$  (typ.). An integrated output sink current circuitry keeps the voltage at the Output pin Q below 5.5 V even when reverse currents are applied. Thus connected devices are protected from overvoltage damage.

Type	Package	Marking
IFX24401TEV50	PG-T0252-5	2440150
IFX24401ELV50	PG-SSOP-14	24401V50

## 2 Block Diagram

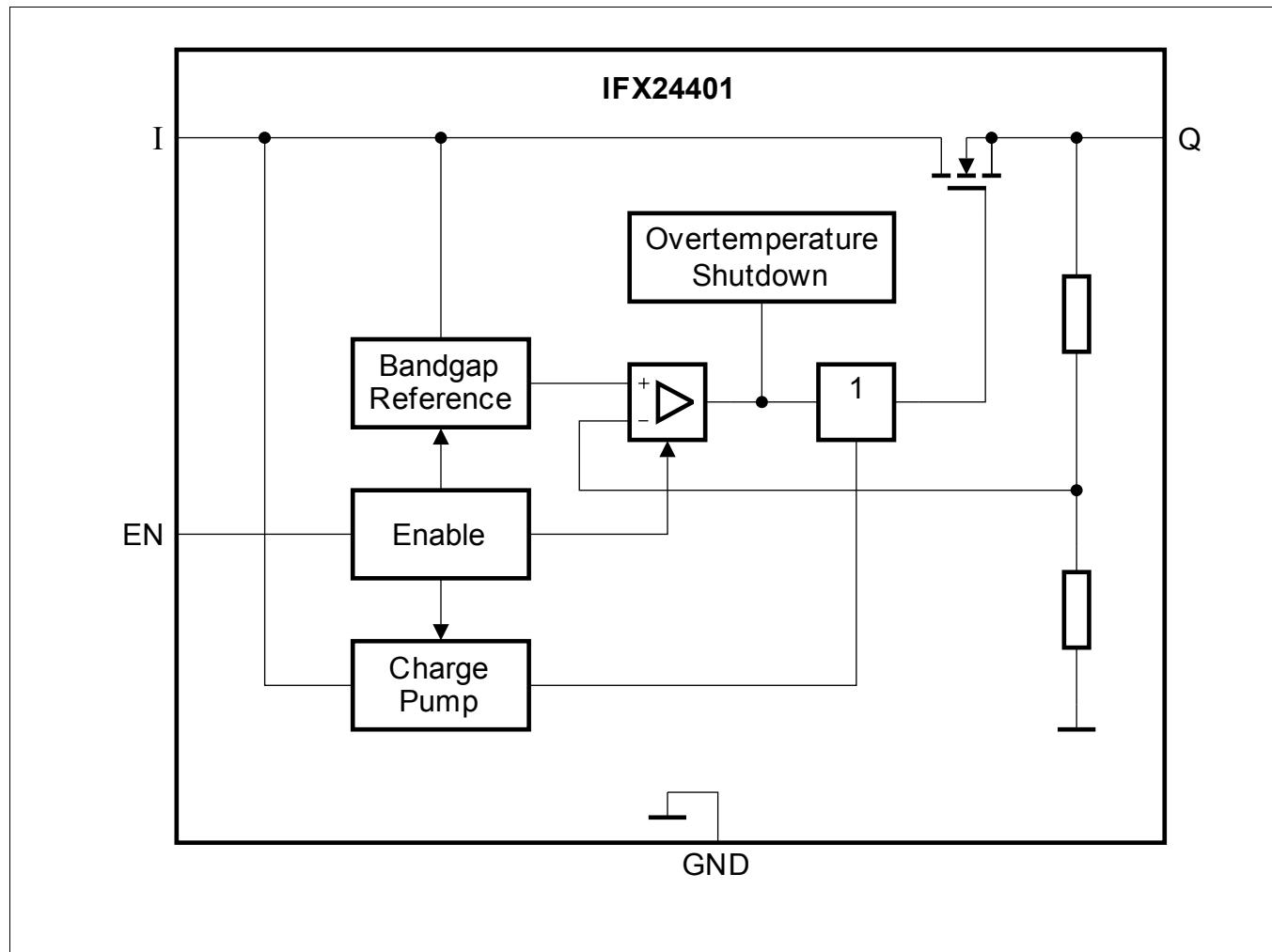


Figure 1 Block Diagram

### 3 Pin Configuration

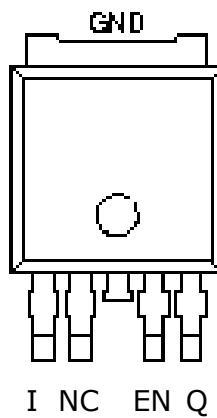
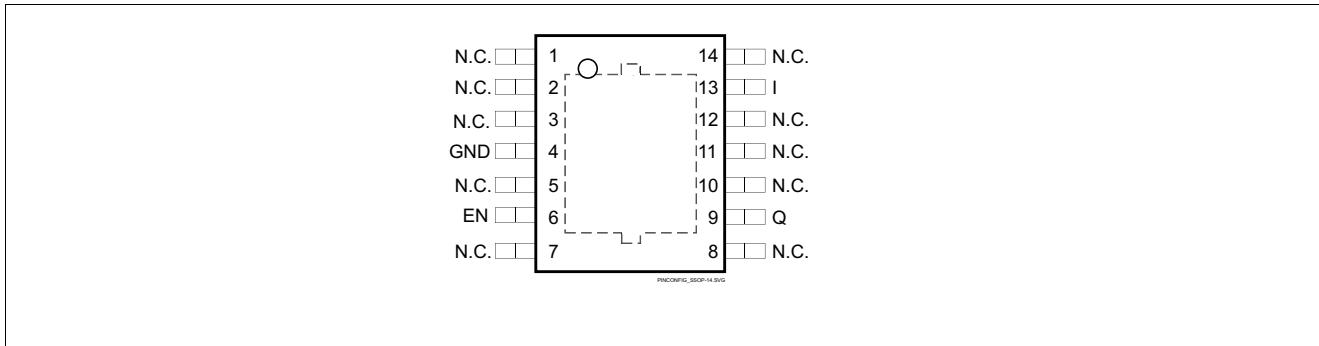


Figure 2 Pin Configuration PG-TO252-5 (top view)

#### 3.1 Pin Definitions and Functions (PG-TO252-5 )

Pin	Symbol	Function
1	I	<b>Input</b> Connect ceramic capacitor between I and GND
2	N.C.	<b>No Connect</b> May be open or connected to GND
3	GND	<b>Ground</b> Internally connected to heat slug
4	EN	<b>Enable Input</b> Low signal level disables the regulator. Pull-down resistor is integrated.
5	Q	<b>Output</b> Place capacitor between Q pin and GND. Capacitor placement should be close to pin. Refer to capacitance and ESR requirements in “ <a href="#">Functional Range” on Page 6</a>
Heat Slug	--	<b>Heat Slug</b> Connect to board GND and heatsink



**Figure 3 Pin Configuration PG-SSOP-14 (top view)**

### 3.2 Pin Definitions and Functions (PG-SSOP-14 )

Pin	Symbol	Function
1,2,3,5,7	N.C.	<b>No Connect</b> May be open or connected to GND
4	GND	<b>Ground</b>
6	EN	<b>Enable Input</b> Low signal level disables the regulator. Pull-down resistor is integrated.
8,10,11,1 2,14	N.C.	<b>No Connect</b> May be open or connected to GND
9	Q	<b>Output</b> Place capacitor between Q pin and GND. Capacitor placement should be close to pin. Refer to capacitance and ESR requirements in " <a href="#">Functional Range</a> " on Page 6
13	I	<b>Input</b> Connect ceramic capacitor between I and GND
Pad		<b>Exposed Pad</b> Connect to board GND and heatsink

## 4 General Product Characteristics

### 4.1 Absolute Maximum Ratings

#### Absolute Maximum Ratings<sup>1)</sup>

$T_j = -40^\circ\text{C}$  to  $150^\circ\text{C}$ ; all voltages with respect to ground, positive current flowing into pin (unless otherwise specified)

Parameter	Symbol	Limit Values		Unit	Test Condition
		Min.	Max.		
<b>Input I</b>					
Voltage	$V_I$	-0.3	45	V	-
Current	$I_I$	-1	-	mA	-
<b>Enable EN</b>					
Voltage	$V_{EN}$	-0.3	45	V	Observe current limit $I_{EN,max}^{2)}$
Current	$I_{EN}$	-1	1	mA	-
<b>Output Q</b>					
Voltage	$V_Q$	-0.3	5.5	V	-
Voltage	$V_Q$	-0.3	6.2	V	$t < 10 \text{ s}^{3)}$
Current	$I_Q$	-1	-	mA	-
<b>Temperature</b>					
Junction temperature	$T_j$	-40	150	°C	-
Storage temperature	$T_{stg}$	-50	150	°C	-

1) Not subject to production test, specified by design.

2) External resistor required to keep current below absolute maximum rating when voltages  $\geq 5.5 \text{ V}$  are applied.

3) Exposure to these absolute maximum ratings for extended periods ( $t > 10 \text{ s}$ ) may affect device reliability.

*Note: Stresses above the ones listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.*

*Note: Integrated protection functions are designed to prevent IC destruction under fault conditions described in the data sheet. Fault conditions are considered as "outside" normal operating range. Protection functions are not designed for continuous repetitive operation.*

### 4.2 Functional Range

Parameter	Symbol	Limit Values		Unit	Remarks
		Min.	Max.		
Input voltage	$V_I$	5.5	42	V	-
Junction temperature	$T_j$	-40	125	°C	-
Output Capacitor	$C_Q$	470	-	nF	<sup>1)</sup>
	ESR ( $C_Q$ )	-	10	Ω	f = 10 kHz

1) The minimum output capacitance requirement is applicable for a worst case capacitor tolerance of 30%

*Note: In the operating range, the functions given in the circuit description are fulfilled.*

## General Product Characteristics

## 4.3 Thermal Resistance

Pos.	Parameter	Symbol	Limit Value			Unit	Conditions
			Min.	Typ.	Max.		
<b>IFX24401TEV50 (PG-TO252-5, )</b>							
4.3.1	Junction to Case <sup>1)</sup>	$R_{thJC}$	—	4	—	K/W	measured to pin 5
4.3.2	Junction to Ambient <sup>1)</sup>	$R_{thJA}$	—	115	—	K/W	Footprint only <sup>2)</sup>
4.3.3			—	57	—	K/W	300mm <sup>2</sup> heatsink area on PCB <sup>2)</sup>
4.3.4			—	42	—	K/W	600mm <sup>2</sup> heatsink area on PCB <sup>2)</sup>
<b>IFX24401ELV50 (PG-SSOP-14)</b>							
4.3.5	Junction to Case <sup>1)</sup>	$R_{thJC}$	—	7	—	K/W	measured to pin 5
4.3.6	Junction to Ambient <sup>1)</sup>	$R_{thJA}$	—	120	—	K/W	Footprint only <sup>2)</sup>
4.3.7			—	59	—	K/W	300mm <sup>2</sup> heatsink area on PCB <sup>2)</sup>
4.3.8			—	49	—	K/W	600mm <sup>2</sup> heatsink area on PCB <sup>2)</sup>

1) not subject to production test, specified by design

2) EIA/JESD 52\_2, FR4, 80 × 80 × 1.5 mm; 35µ Cu, 5µ Sn

**Table 1 Electrical Characteristics**

$V_I = 13.5 \text{ V}$ ;  $V_{EN} = 5 \text{ V}$ ;  $-40^\circ\text{C} < T_j < 125^\circ\text{C}$  (unless otherwise specified)

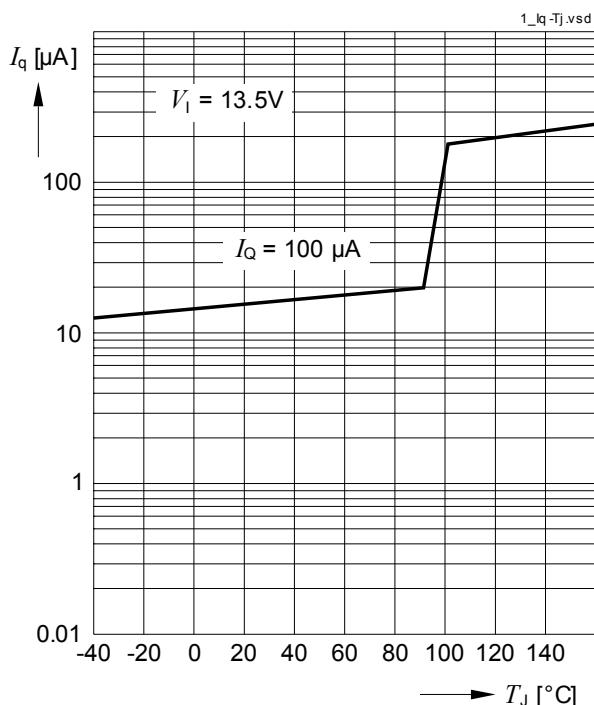
Parameter	Symbol	Limit Values			Unit	Measuring Condition
		Min.	Typ.	Max.		
<b>Output Q</b>						
Output voltage	$V_Q$	4.9	5.0	5.1	V	$0.1 \text{ mA} < I_Q < 300 \text{ mA}$ ; $6 \text{ V} < V_I < 16 \text{ V}$
Output voltage	$V_Q$	4.9	5.0	5.1	V	$0.1 \text{ mA} < I_Q < 100 \text{ mA}$ ; $6 \text{ V} < V_I < 40 \text{ V}$
Output current limit	$I_{Q,LIM}$	320	–	–	mA	<sup>1)</sup>
Output current limit	$I_{Q,LIM}$	–	–	800	mA	$V_Q = 0 \text{ V}$
Current consumption; $I_q = I_I - I_Q$	$I_q$	–	20	30	$\mu\text{A}$	$I_Q = 0.1 \text{ mA}$ ; $T_j = 25^\circ\text{C}$
Current consumption; $I_q = I_I - I_Q$	$I_q$	–	–	40	$\mu\text{A}$	$I_Q = 0.1 \text{ mA}$ ; $T_j \leq 80^\circ\text{C}$
Quiescent current; Disabled	$I_q$	–	5	9	$\mu\text{A}$	$V_{EN} = 0 \text{ V}$ ; $T_j < 80^\circ\text{C}$
Drop voltage	$V_{dr}$	–	250	500	mV	$I_Q = 200 \text{ mA}$ ; $V_{dr} = V_I - V_Q$ <sup>1)</sup>
Load regulation	$\Delta V_{Q,lo}$	-40	15	40	mV	$I_Q = 5 \text{ mA}$ to $250 \text{ mA}$
Line regulation	$\Delta V_{Q,li}$	-20	5	20	mV	$V_I = 10 \text{ V}$ to $32 \text{ V}$ ; $I_Q = 5 \text{ mA}$
Power supply ripple rejection	$PSRR$	–	60	–	dB	$f_r = 100 \text{ Hz}$ ; $V_r = 0.5 \text{ Vpp}$
Temperature output voltage drift	$dV_Q/dT$	–	0.5	–	mV/K	–
<b>Enable Input EN</b>						
Turn-on Voltage	$V_{EN\ ON}$	3.1	–	–	V	$V_Q \geq 4.9 \text{ V}$
Turn-off Voltage	$V_{EN\ OFF}$	–	–	0.8	V	$V_Q \leq 0.3 \text{ V}$
H-input current	$I_{EN\ ON}$	–	3	4	$\mu\text{A}$	$V_{EN} = 5 \text{ V}$
L-input current	$I_{EN\ OFF}$	–	0.5	1	$\mu\text{A}$	$V_{EN} = 0 \text{ V}$ ; $T_j < 80^\circ\text{C}$

1) Measured when the output voltage  $V_Q$  has dropped 100 mV from the nominal value obtained at  $V_I = 13.5 \text{ V}$ .

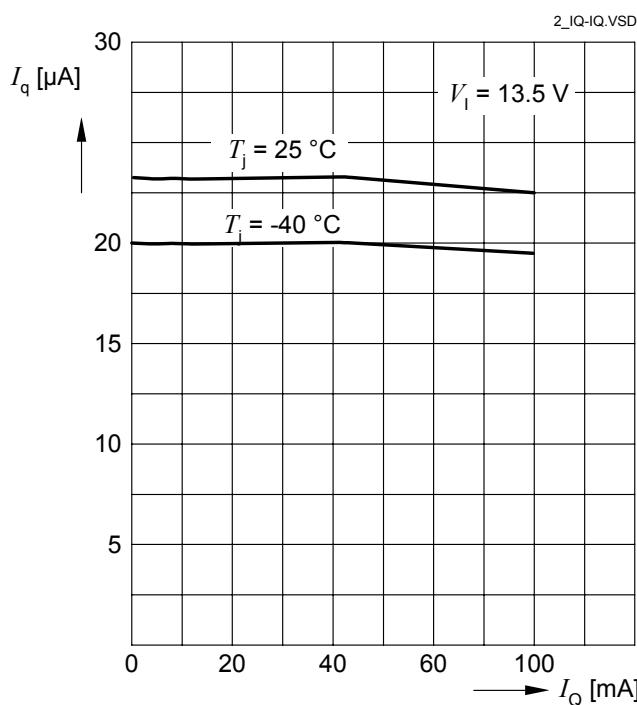
## Typical Performance Characteristics

## 5 Typical Performance Characteristics

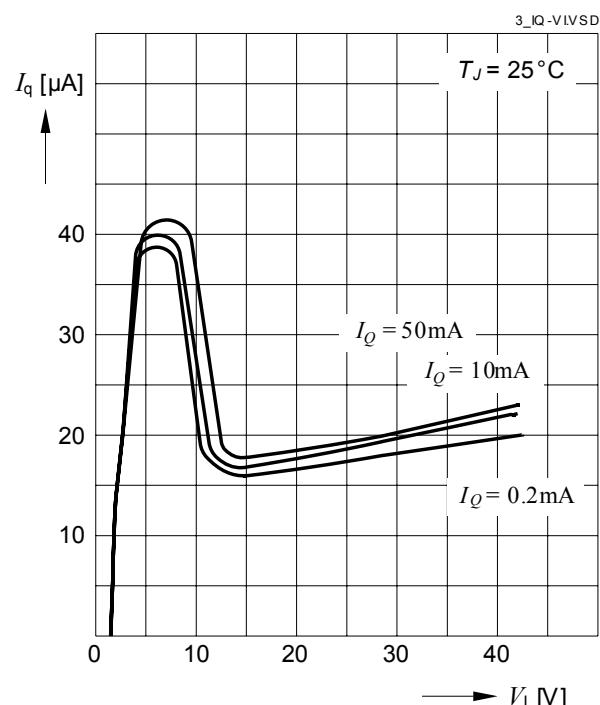
**Current Consumption  $I_q$  versus Junction Temperature  $T_j$**



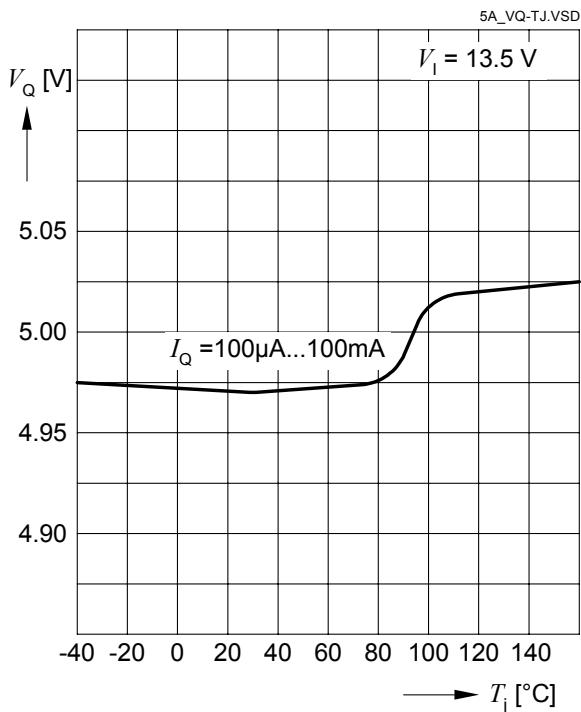
**Current Consumption  $I_q$  versus Output Current  $I_Q$**



**Current Consumption  $I_q$  versus Input Voltage  $V_i$**

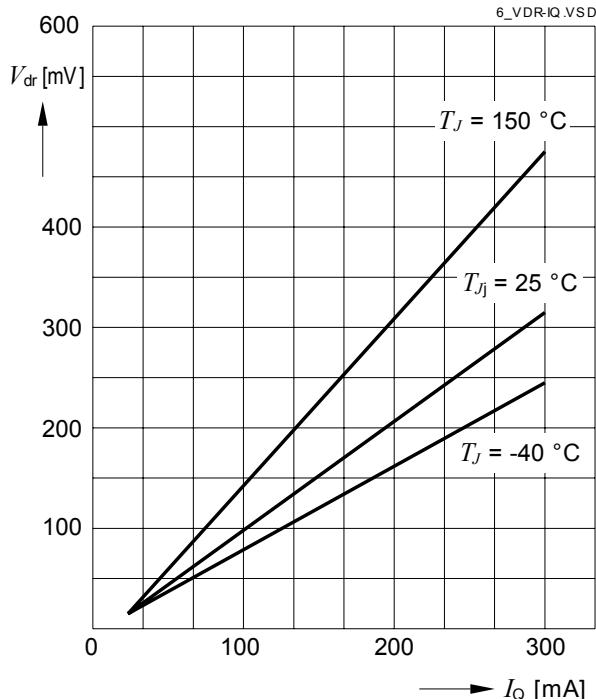


**Output Voltage  $V_Q$  versus Junction Temperature  $T_j$**

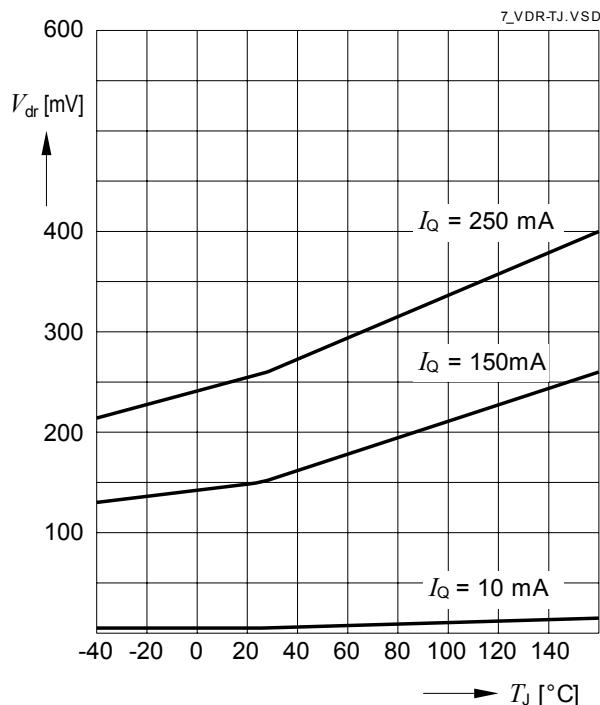


### Typical Performance Characteristics

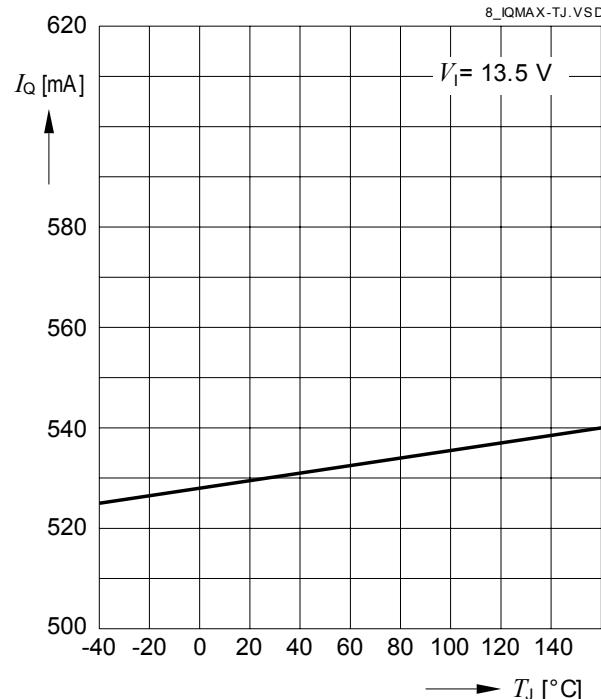
**Dropout Voltage  $V_{dr}$  versus Output Current  $I_Q$**



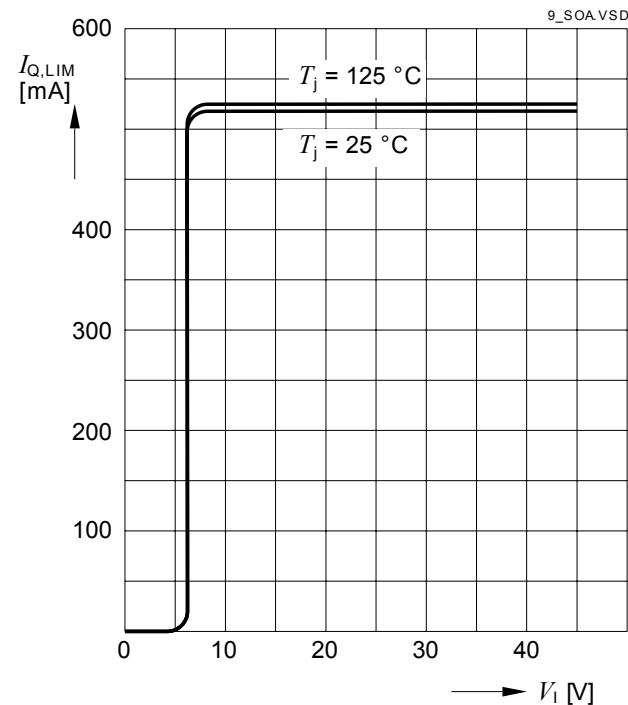
**Dropout Voltage  $V_{dr}$  versus Junction Temperature**



**Maximum Output Current  $I_Q$  versus Junction Temperature  $T_j$**

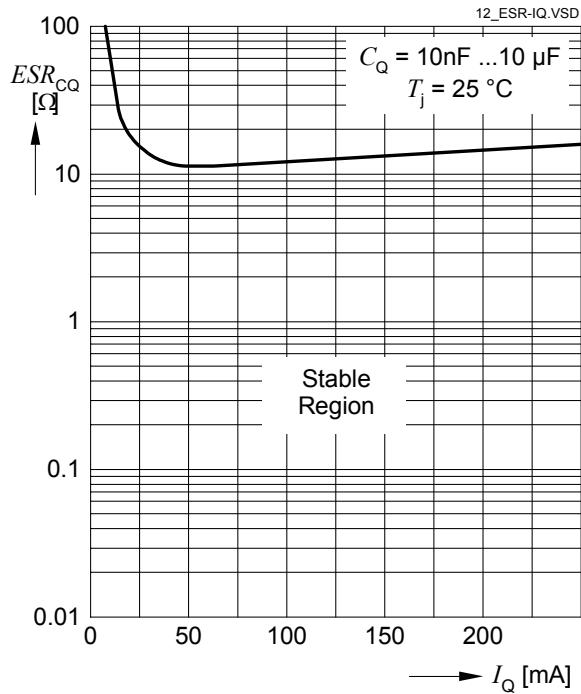
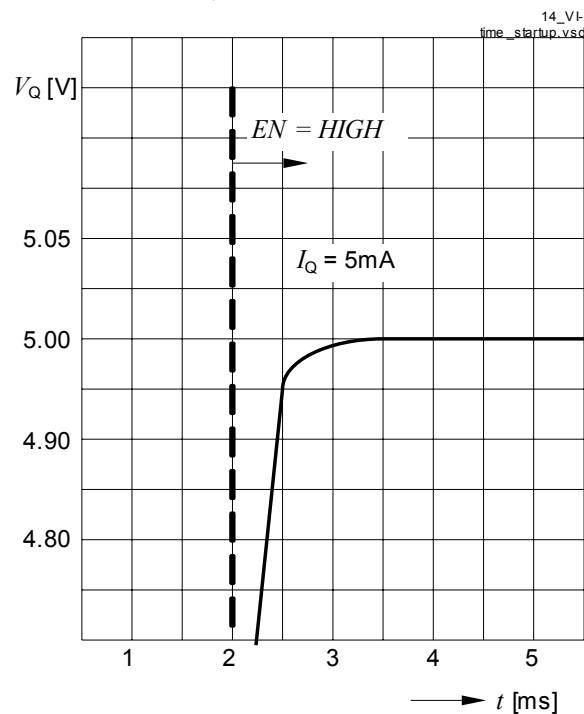


**Maximum Output Current  $I_Q$  versus Input Voltage  $V_i$**

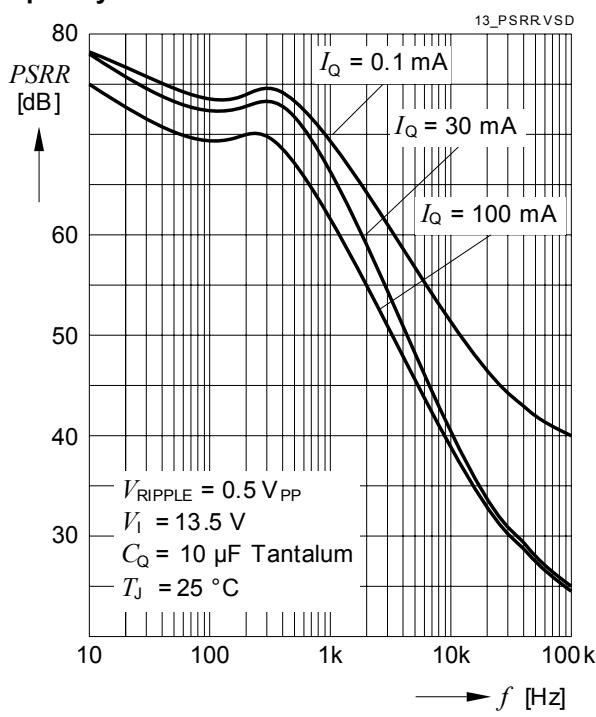
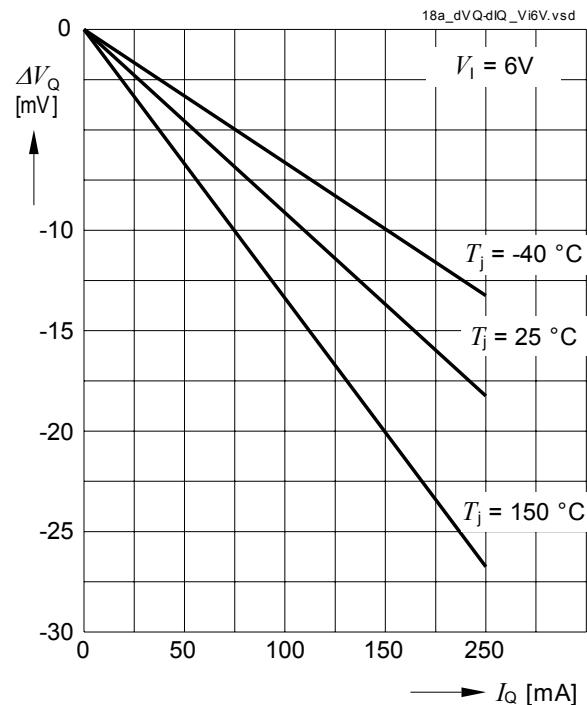


## Typical Performance Characteristics

## Region of Stability

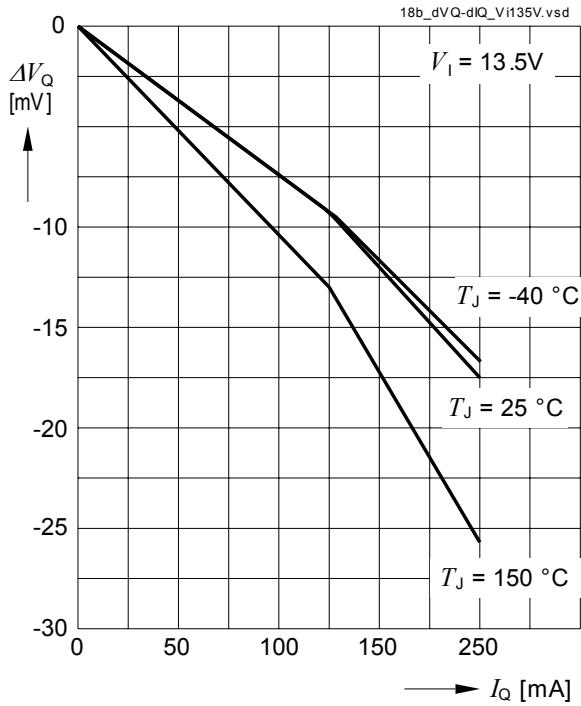

Output Voltage  $V_Q$  Start-up behavior


## Power Supply Ripple Rejection PSRR versus Frequency f

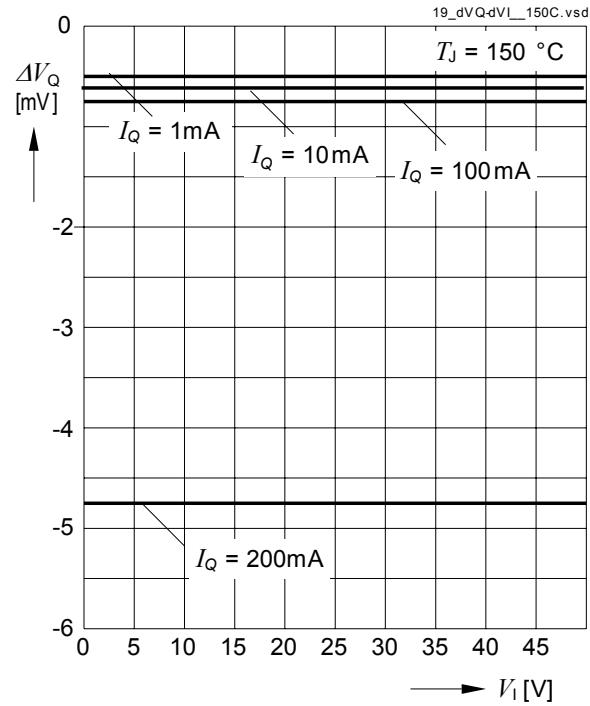

Load Regulation  $\Delta V_Q$  versus Output Current Change  $\Delta I_Q$ 


### Typical Performance Characteristics

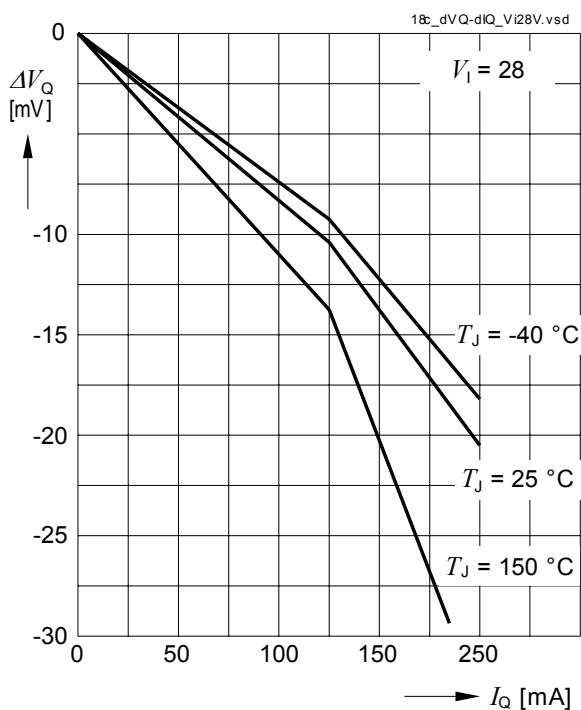
**Load Regulation  $\Delta V_Q$  versus Output Current Change  $dI_Q$**



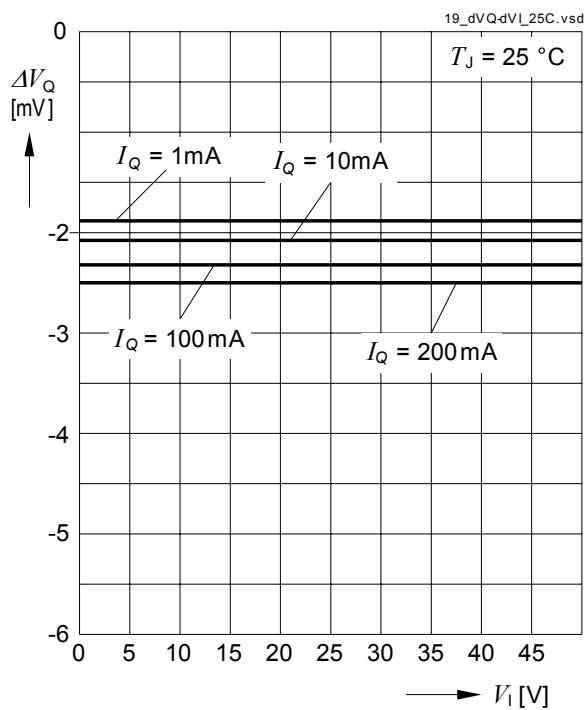
**Line Regulation  $\Delta V_Q$  versus Input Voltage Changed  $V_I$**



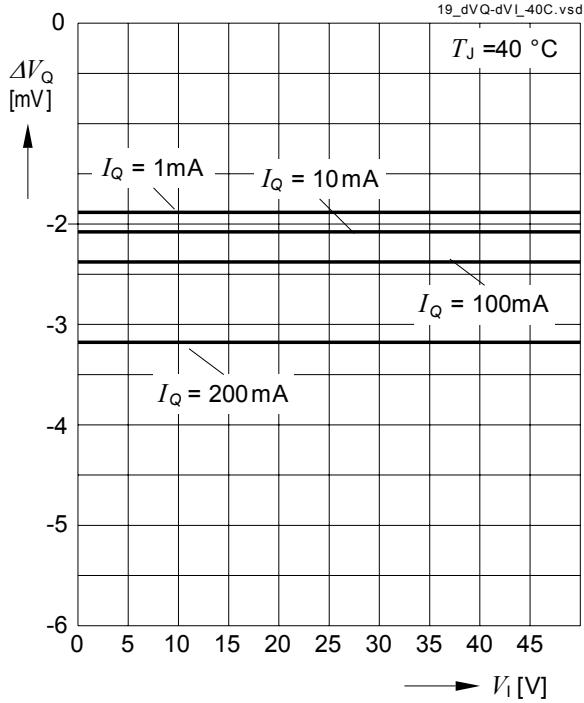
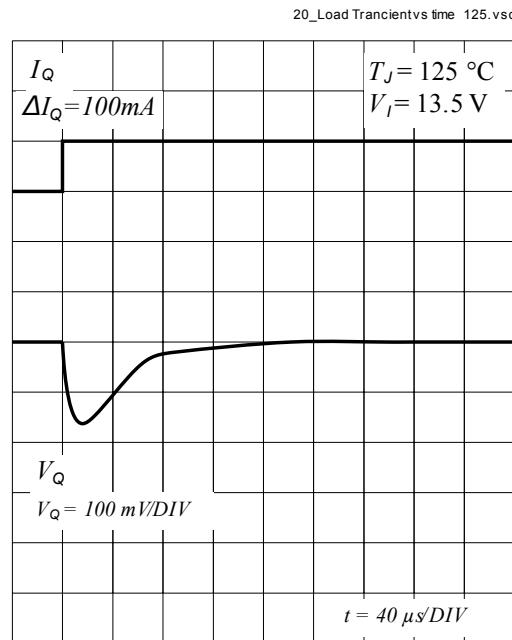
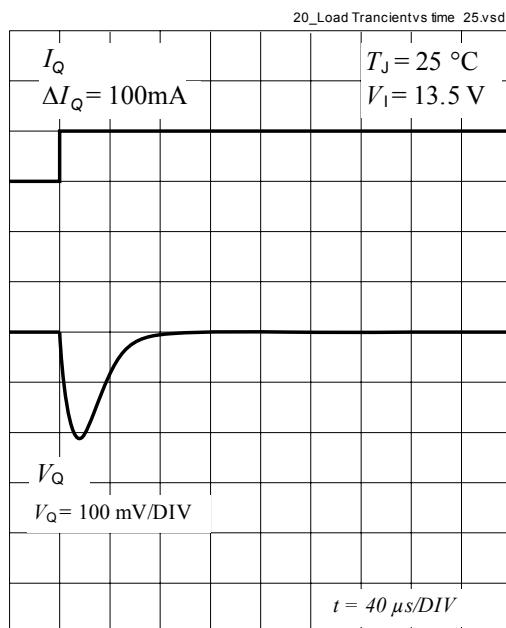
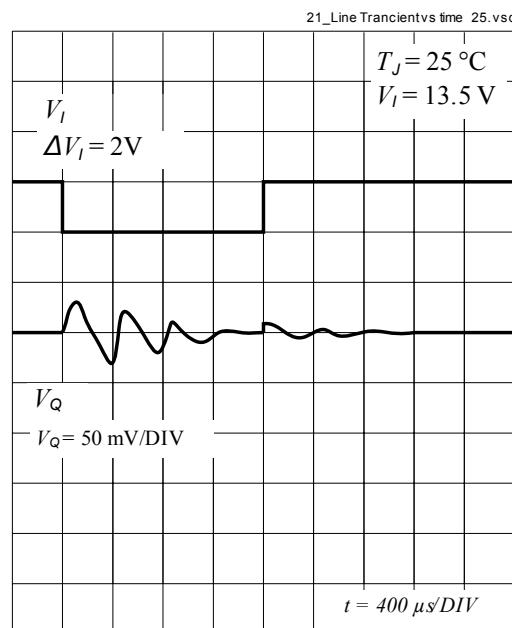
**Load Regulation  $\Delta V_Q$  versus Output Current Change  $\Delta I_Q$**



**Line Regulation  $\Delta V_Q$  versus Input Voltage Changed  $V_I$**



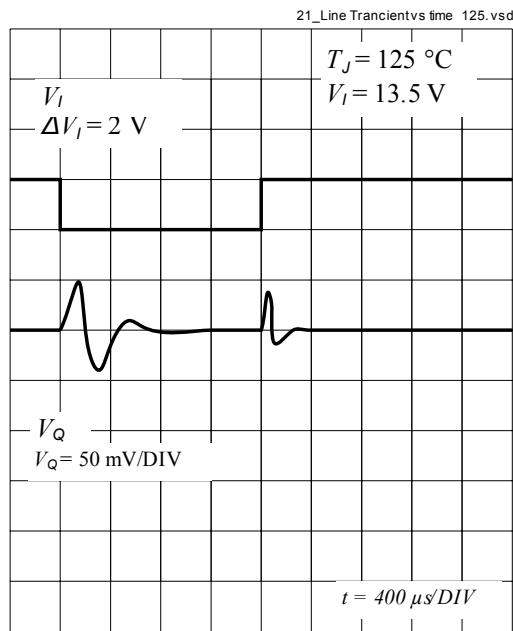
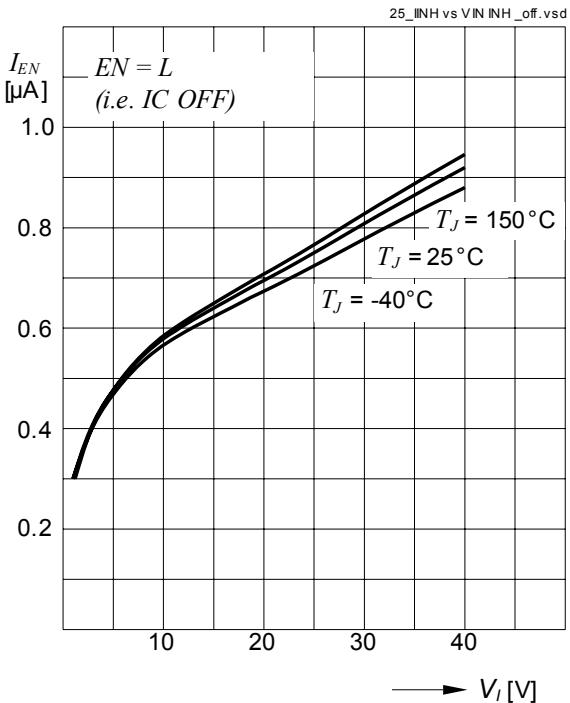
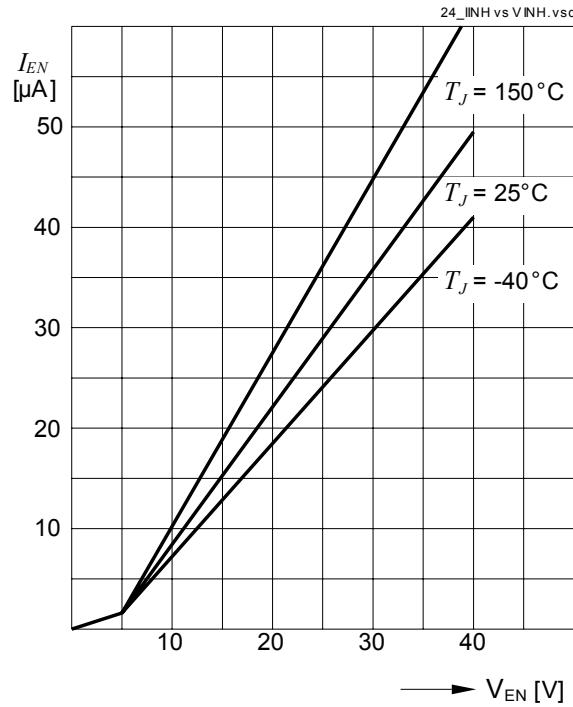
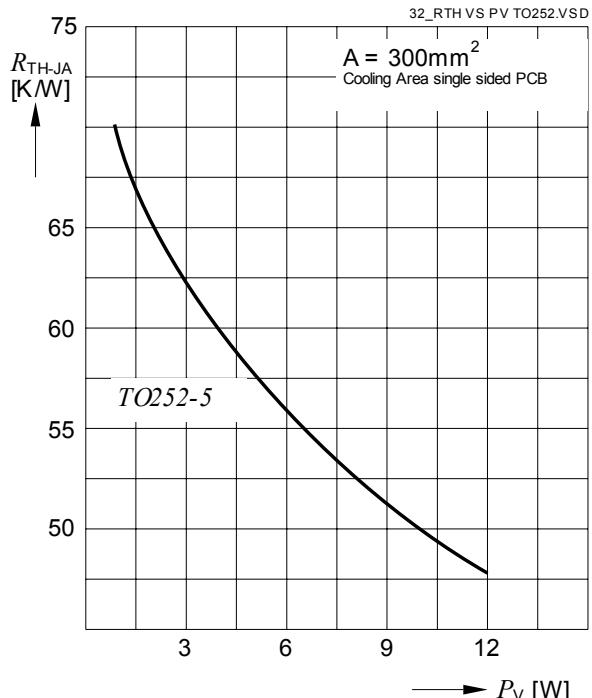
## Typical Performance Characteristics

Line Regulation  $\Delta V_Q$  versus  
Input Voltage Change  $V_I$ 

Load Transient Response Peak Voltage  $\Delta V_Q$ 

Load Transient Response Peak Voltage  $\Delta V_Q$ 

Line Transient Response Peak Voltage  $\Delta V_Q$ 


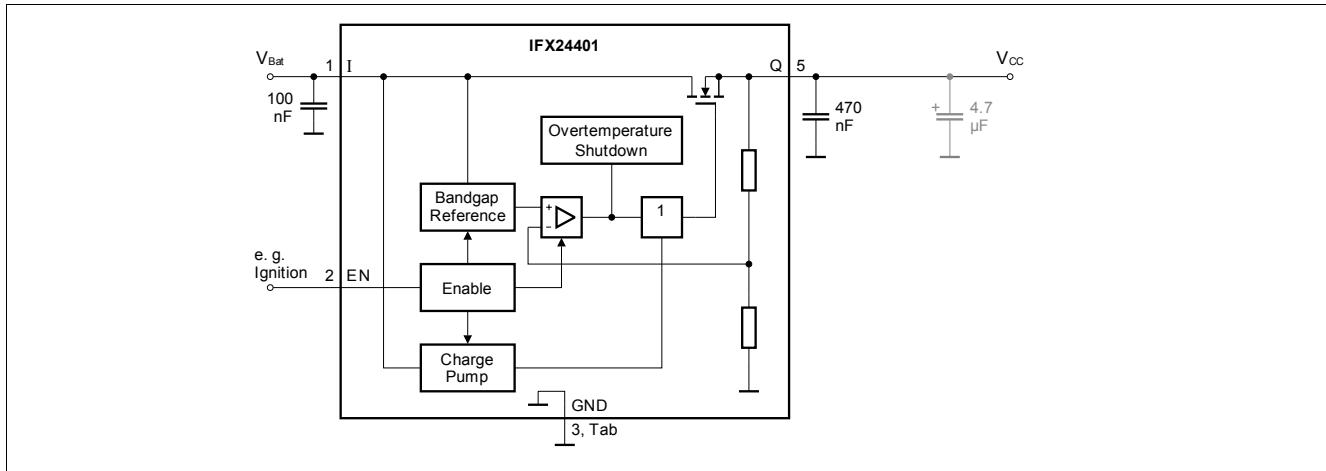
## Typical Performance Characteristics

Line Transient Response Peak Voltage  $\Delta V_Q$ 

!


Enabled Input Current  $I_{EN}$  versus  
Input Voltage  $V_I$ , EN=Off

Enabled Input Current  $I_{EN}$  versus  
Enabled Input Voltage  $V_{EN}$ 

Thermal Resistance Junction-Ambient  $R_{THJA}$   
versus Power Dissipation  $P_V$ 


## 6 Application Information



**Figure 4 Application Diagram**

### Input, Output

An input capacitor is necessary for damping line influences. A resistor of approx.  $1\ \Omega$  in series with  $C_i$ , can damp the LC of the input inductivity and the input capacitor.

The IFX24401 requires a ceramic output capacitor of at least 470 nF. In order to damp influences resulting from load current surges it is recommended to add an additional electrolytic capacitor of 4.7  $\mu\text{F}$  to 47  $\mu\text{F}$  at the output as shown in [Figure 4](#).

Additionally a buffer capacitor  $C_B$  of  $> 10\mu\text{F}$  should be used for the output to suppress influences from load surges to the voltage levels. This one can either be an aluminum electrolytic capacitor or a tantalum capacitor following the application requirements.

A general recommendation is to keep the drop over the equivalent serial resistor (ESR) together with the discharge of the blocking capacitor below the allowed Headroom of the Application to be supplied (e.g. typ.  $dV_Q = 350\text{mV}$ ).

Since the regulator output current roughly rises linearly with time the discharge of the capacitor can be calculated as follows:

$$dV_{C_B} = dI_Q * dt / C_B$$

The drop across the ESR calculates as:

$$dV_{\text{ESR}} = dI * \text{ESR}$$

To prevent a reset the following relationship must be fulfilled:

$$dV_C + dV_{\text{ESR}} < V_{RH} = 350\text{mV}$$

Example: Assuming a load current change of  $dI_Q = 100\text{mA}$ , a blocking capacitor of  $C_B = 22\mu\text{F}$  and a typical regulator reaction time under normal operating conditions of  $dt \sim 25\mu\text{s}$  and for special dynamic load conditions, such as load step from very low base load, a reaction time of  $dt \sim 75\mu\text{s}$ .

$$dV_C = dI_Q * dt / C_B = 100\text{mA} * 25\mu\text{s} / 22\mu\text{F} = 113\text{mV}$$

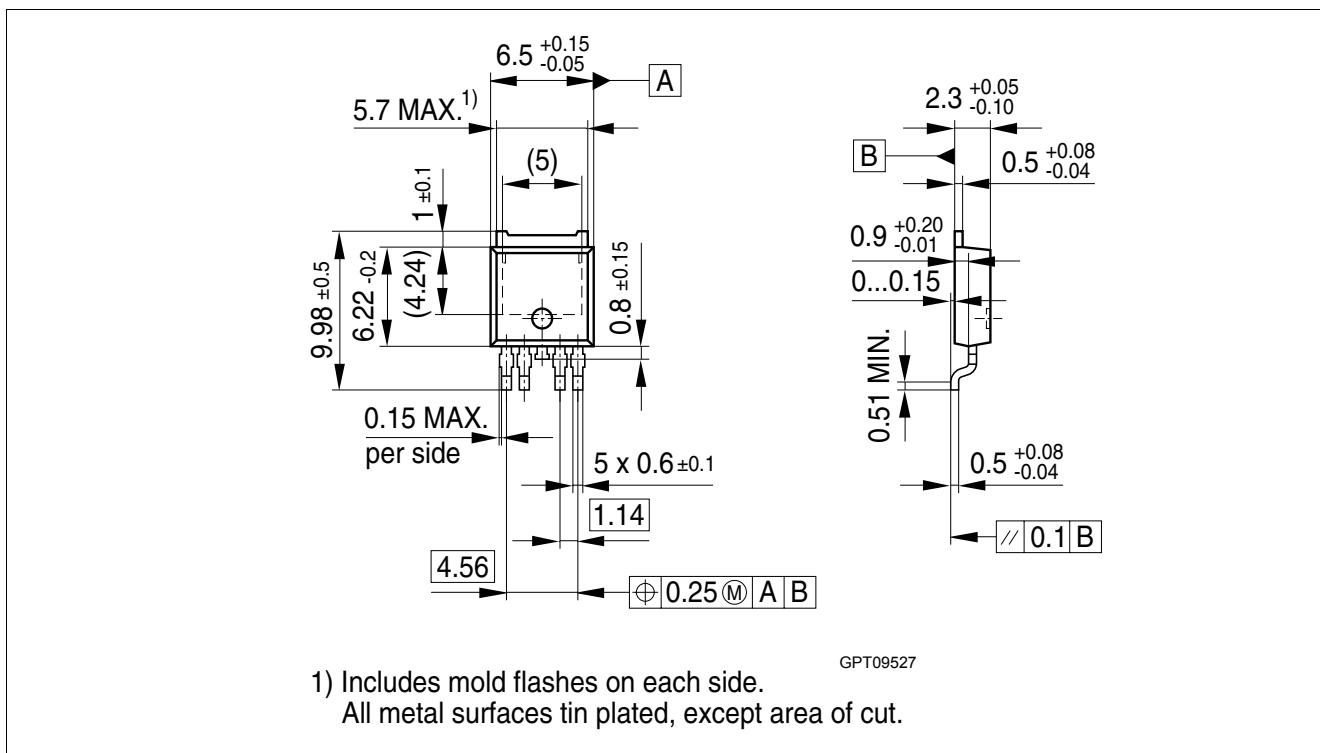
So for the ESR we can allow

$$dV_{\text{ESR}} = V_{RH2} - dV_C = 350\text{mV} - 113\text{mV} = 236\text{mV}$$

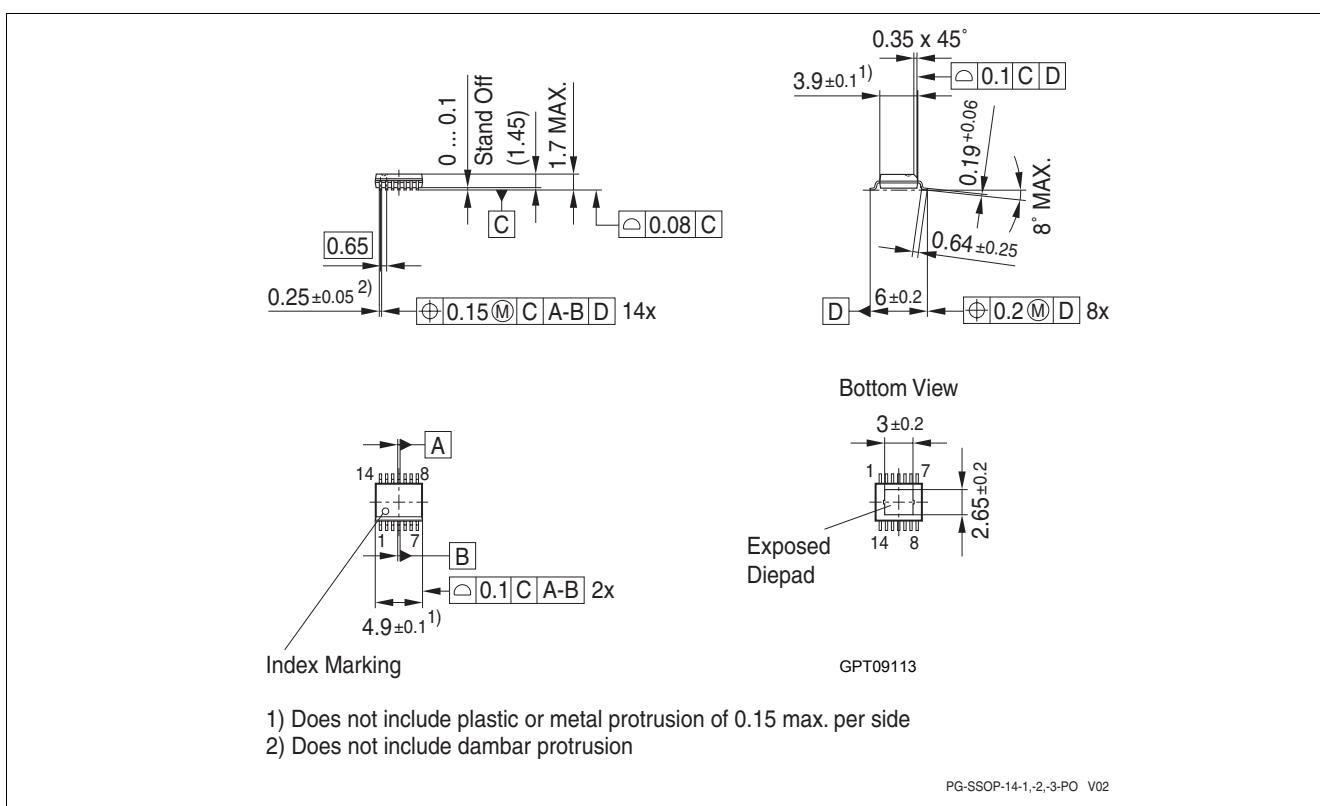
The permissible ESR becomes:

$$\text{ESR} = dV_{\text{ESR}} / dI_Q = 236\text{mV} / 100\text{mA} = 2.36\text{Ohm}$$

## 7 Package Outlines



**Figure 5 PG-TQ252-5**



## 8 Revision History

Revision	Date	Changes
1.02	2009-12-10	Corrections to pin assignment
1.01	2009-10-19	Coverpage changed Overview page: Inserted reference statement to TLE/TLF series.
1.0	2009-04-28	Initial Release

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[AP2113KTR-G1](#) [AP2111H-1.2TRG1](#) [ZLDO1117QK50TC](#) [AZ1117IH-1.8TRG1](#) [TCR3DG12,LF](#) [MIC5514-3.3YMT-T5](#) [MIC5512-1.2YMT-](#)  
[T5](#) [MIC5317-2.8YM5-T5](#) [SCD7912BTG](#) [NCP154MX180270TAG](#) [SCD33269T-5.0G](#) [NCV8170BMX330TCG](#) [NCV8170AMX120TCG](#)  
[NCP706ABMX300TAG](#) [NCP153MX330180TCG](#) [NCP114BMX075TCG](#) [MC33269T-3.5G](#) [CAT6243-ADJCMT5T](#) [TCR3DG33,LF](#)  
[AP2127N-1.0TRG1](#) [TCR4DG35,LF](#) [LT1117CST-3.3](#) [LT1117CST-5](#) [TAR5S15U\(TE85L,F\)](#) [TAR5S18U\(TE85L,F\)](#) [TCR3UG19A,LF](#)  
[TCR4DG105,LF](#) [NCV8170AMX360TCG](#) [MIC94310-NYMT-T5](#) [TLE4268GSXUMA2](#) [NCV8186BMN175TAG](#) [NCP715SQ15T2G](#)  
[MIC5317-3.0YD5-T5](#) [NCV563SQ18T1G](#) [MIC5317-2.8YD5-T5](#) [NCP715MX30TBG](#)